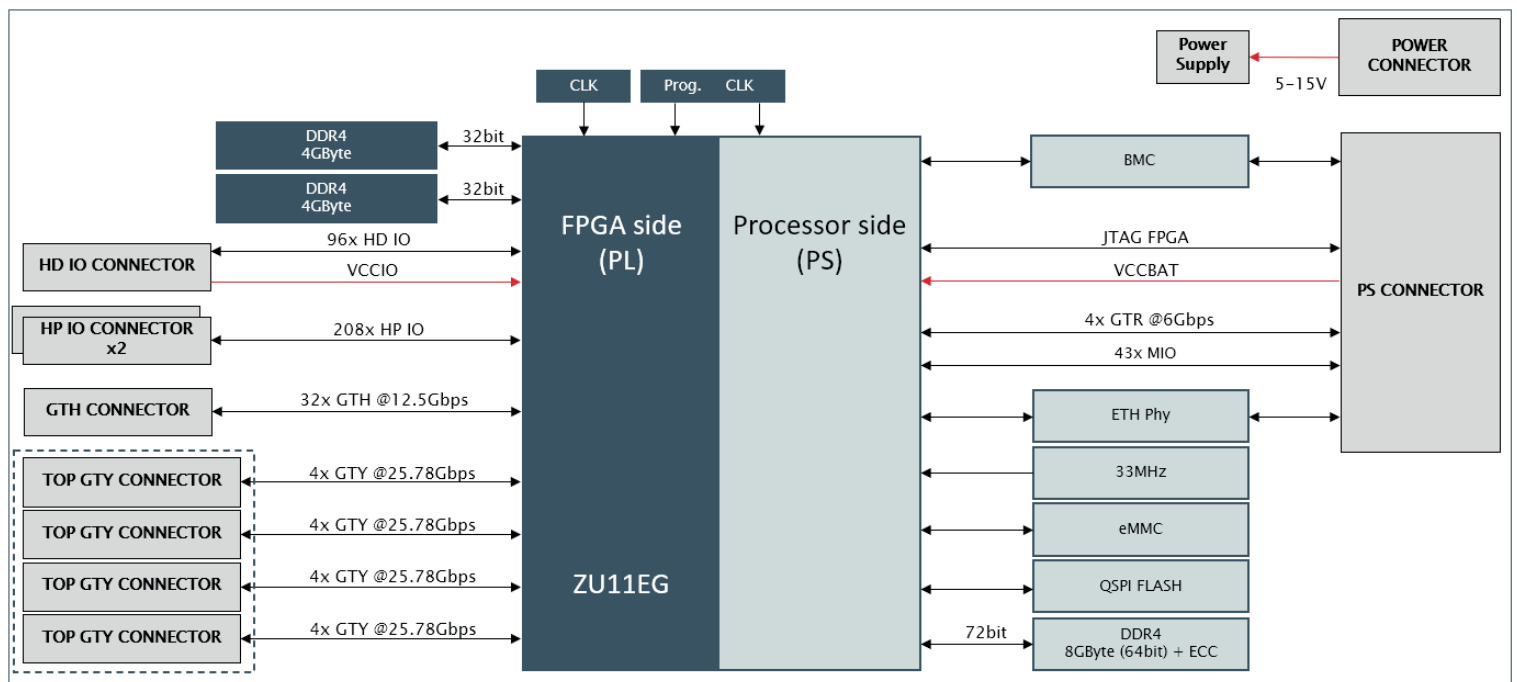
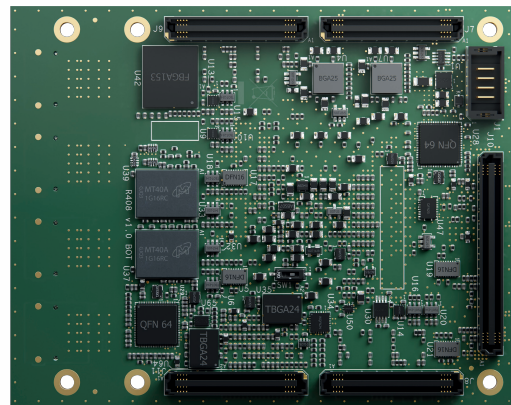




Zeus Zynq® UltraScale+™ MPSoC System-on-Module



- Zynq® UltraScale+™ MPSoC ZU11EG
- PCIe Gen2 x4 Root Complex
 - PCIe Gen3 x16 End Point
- Quad-Core ARM Cortex-A53

- 304 SE IOs total (96 LVDS)
- 16 GTY @25.78Gbps (Top side)
- 32 GTH @12.5Gbps (Bot side)
- 3x DDR4 banks, 16GByte Total
 - Industrial Temp Grade
 - Long Term Supply

- Software Defined Radio
 - Radar Systems
 - Electronic Warfare
- High Precision Measurement
 - "Customizable"

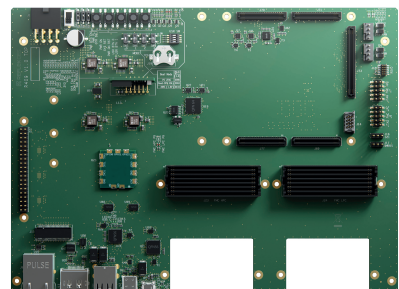
Features	Zeus Zynq® UltraScale+™ MPSoC	
FPGA SoC	XCZU11EG-1FFVC1760I device Programmable Logic 650 KLC, Block RAM 21.1MB, UltraRAM 22.5Mb, 2928 DSP Slices FPGA speed grade 1, Industrial Temp Range Quad-core ARM Cortex-A53 MPCore @1.2GHz Dual-core ARM Cortex-R5 MPCore @500MHz Mali™-400 MP2 @600MHz	
DDR4 Memory	PL= 2 banks 4GByte each @2400MT/s, x32bit	
	PS= 1 bank 8GByte @2400 MT/s, x64bit + x8bit ECC	
PS Communication & Networking	10/100/1000 Base-T Ethernet RGMII 43x MIO (NAND flash, eMMC or SD card, ETH RGMII, USB, SPI, I2C, UART, GPIO)	
Top Connectors	High Speed Accelerate connectors (GTY)	4x 4 serial transceivers channel (RX and TX) @25.78Gbps (Existing cable adapter to QSFP+ and SFP+ connectors)
Bottom Connectors	Processor (PS) Mezzanine connector	4x serial transceivers channel (RX and TX) @6Gbps PCIe Gen2 x4 Root Complex capable 43x MIO
	GTH Mezzanine connector	32x serial transceivers channel (RX and TX) @12.5Gbps PCIe Gen3 x16 End Point capable
	HP Mezzanine connectors	208x HP I/O high speed up to 1260 Mb/s, designed for high-speed chip-to-chip interfaces with voltages up to 1.8V 96x LVDS capability
	HD Mezzanine connector	96x HD I/O low speed up to 250 Mb/s, designed to support low-speed interfaces with voltages 3.3V, 2.5V, 1.8V, 1.2V
FPGA Configuration	JTAG available on Processor (PS) Mezzanine connector	
	Quad SPI 2x1Gbit NOR Flash for non-volatile storage, remote upgrade and failsafe configuration	
Software Configuration	128GByte NAND Flash eMMC (Stores U-Boot, Linux Kernel, and RootFS)	
Mechanical & Environmental Specification	Module rugged for shocks and high vibration IEC/EN61000 (EMI immunity), EN61000 + EN55032 (EMI emission), EN60068 (Vibration: sinusoidal, 10Hz - 4000Hz, +/- 0.15mm, 2g ; Shock: half-sinusoidal, 11ms, 15g) 5-15V Power Input Industrial temperature grade -40°C to +85°C Conformal coating (option on request)	
Power & Dissipation	70W max, active heatsink (heat spreader + heatsink + fan)	
Board Management Controller	Communication with Carrier board: I2C, UART, SMBus Communication with FPGA : 1x UART to PL, 1x UART to PS Monitoring : Current, voltages, temperature, ID information Programming : Clock, QSPI FPGA, QSPI BMC Control: Power, temperature protection, Fans	
Module dimensions	107mm x 85mm (4 x 3.4 inches) / 12mm thickness (38.6mm with active heatsink and heat spreader)	
Deliverables	Zeus Zynq® UltraScale+™ MPSoC module Active heatsink with heat spreader	
Ordering Information	RXCZUP11EGPF42-SOM01I	

Zeus Carrier Board

The Zeus Carrier board is sold separately
 Ordering information : RXCZUP-CBD0SA

The following deliverables are only included with the purchase of a carrier board :

- PDF Documentation (Starter Guide, Reference Manual, Interconnect pinout file)
- Power supply and cables (US, UK, EU, JP), interface cables (USB, Ethernet)
- Test designs (Vivado II project)
- Linux Kernel & Linaro optimized distribution, U-boot bootloader, Test scripts
- Mechanical drawings, 3D step, assembly files
- Carrier board schematics
- Carrier board Design Guide
- Online support at support.reflexces.com



Zeus Carrier board
170mm x 233.35mm